SPECIFICATION

CUSTO		<u></u> -	L	C2004A-SL	L-JTV
		_			
APPRO			') РСВ	VERSION:	DATA:
SALES B	Y	APPROV	VED BY	CHECKED BY	PREPARED BY
VERSION	D	ATE	REVISE	D S	UMMARY
			PAGE N	0.	

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2.Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) Producer has the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9)Producer has the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions. Producer has the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.

3.General Specification

Item	Dimension	Unit
Number of Characters	20 characters x 4 Lines	_
Module dimension	98.0 x 60.0 x 13.6 (MAX)	mm
View area	77.0 x 25.2	mm
Active area	70.4 x 20.8	mm
Dot size	0.55 x 0.55	mm
Dot pitch	0.60 x 0.60	mm
Character size	2.95 x 4.75	mm
Character pitch	3.55 x 5.35	mm
LCD type	VA TN Negative, Transmissive (In LCD production, It will occur slightly color differently guarantee the same color in the same bate	
Duty	1/16	
View direction	12 o'clock	
Backlight Type	LED, High light white	
IC	ST7066U	
Interface	68 series	

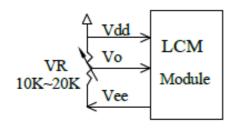
4.Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	Тор	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	T_{ST}	-30	_	+80	$^{\circ}\!\mathbb{C}$
Input Voltage	VI	V _{SS} -0.3	_	V _{DD} +0.3	V
Supply Voltage For Logic	$V_{ m DD} ext{-}V_{ m SS}$	-0.3	_	7	V
Supply Voltage For LCD	V_{DD} - V_{o}	Vss -0.3	_	13	V

5.Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	$ m V_{DD} ext{-}V_{SS}$	_	4.5	5.0	5.5	V
Supply Voltage For LCD		Ta=-20°C	_	_	_	V
*Note	$V_{ m DD} ext{-}V_0$	Ta=25°C	6.2	6.5	6.8	V
		Ta=70°C	_	_	_	V
Input High Volt.	V_{IH}	_	$0.7~\mathrm{V_{DD}}$	_	V_{DD}	V
Input Low Volt.	V_{IL}	_	V_{SS}	_	0.6	V
Output High Volt.	V_{OH}	_	3.9	_	V_{DD}	V
Output Low Volt.	V_{OL}	_	0	_	0.4	V
Supply Current	I_{DD}	V _{DD} =5.0V	2.0	2.5	3.0	mA

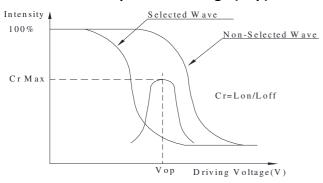
^{*} Note: Please design the VOP adjustment circuit on customer's main board



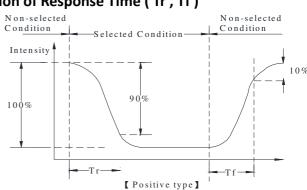
6.Optical Characteristics

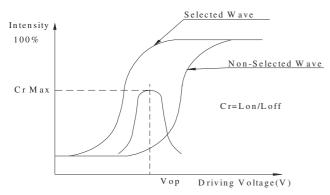
Item	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR≥10	_	60	_	$\phi = 180^{\circ}$
V A 1 -	θ	CR≧10	_	25	_	$\phi = 0^{\circ}$
View Angle	θ	CR≧10	_	40	_	$\phi = 90^{\circ}$
	θ	CR≥10	_	40	_	$\phi = 270^{\circ}$
Contrast Ratio	CR	_	10	_	_	_
D T'	T rise	_	_	300	350	ms
Response Time	T fall	_	_	300	350	ms

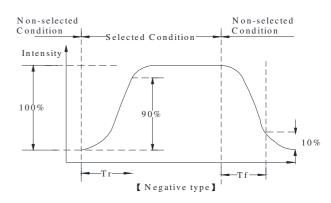
Definition of Operation Voltage (Vop)











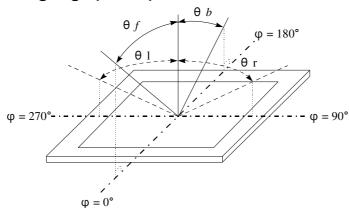
Conditions:

Operating Voltage : Vop

Viewing Angle(θ , φ): 0° , 0°

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

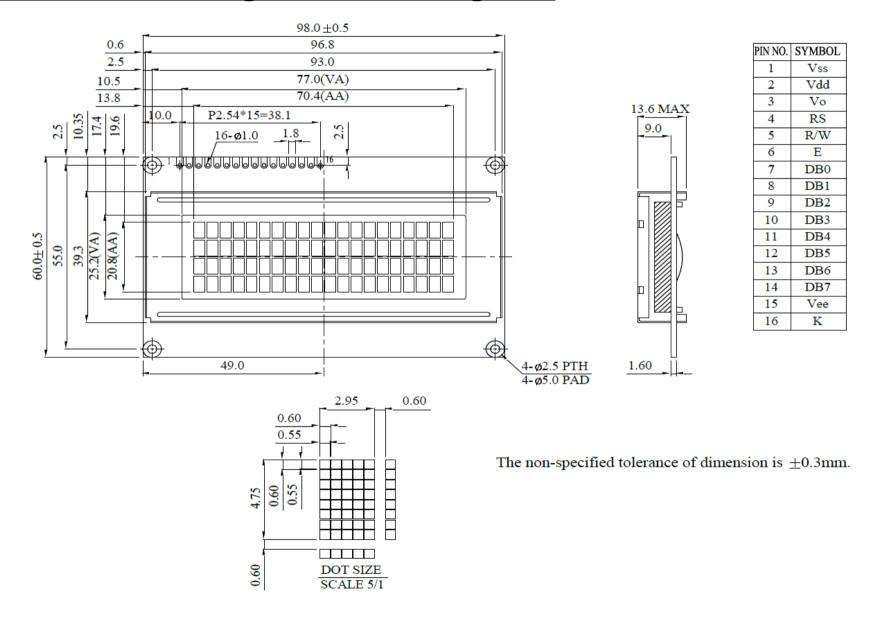
Definition of viewing angle(CR≥2)

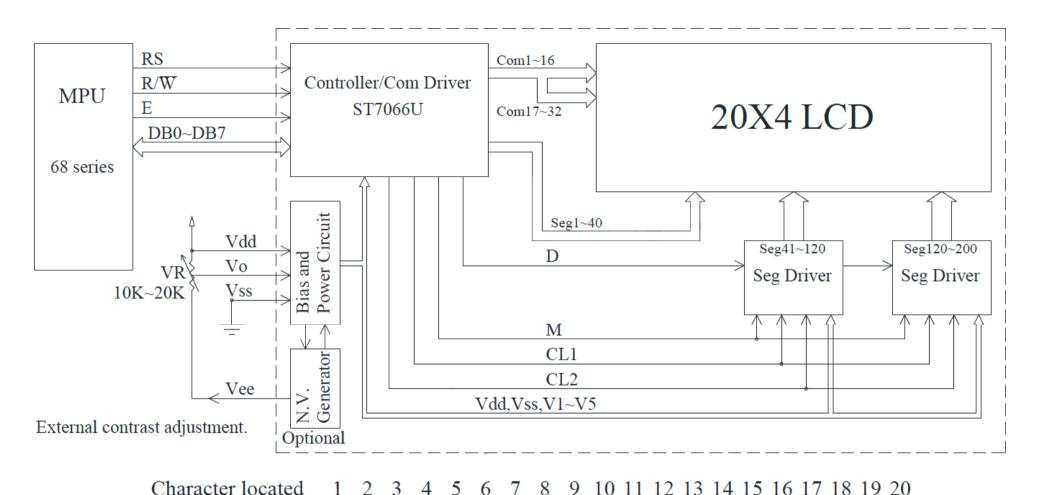


7.Interface Pin Function

Pin No.	Symbol	Level	Description
1	Vss	0V	Ground
2	$ m V_{DD}$	5.0V	Supply Voltage for logic
3	VO	(Variable)	Operating voltage for LCD
4	RS	H/L	H: DATA, L: Instruction code
5	R/W	H/L	H: Read L: Write
6	Е	H,H→L	Chip enable signal
7	DB0	H/L	Data bus line
8	DB1	H/L	Data bus line
9	DB2	H/L	Data bus line
10	DB3	H/L	Data bus line
11	DB4	H/L	Data bus line
12	DB5	H/L	Data bus line
13	DB6	H/L	Data bus line
14	DB7	H/L	Data bus line
15	Vee	_	Negative Voltage Output
16	K	_	Power supply for B/L(-)

8.Contour Drawing & Block Diagram





DDRAM address
DDRAM address
DDRAM address
DDRAM address

1	2	3	4	3	6	/	8	9	10	11	12	13	14	13	16	1 /	18	19	20
00	01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E	0F	10	11	12	13
40	41	42	43	44	45	46	47	48	49	4A	4B	4C	4D	4 E	4F	50	51	52	53
14	15	16	17	18	19	1A	1B	1C	1D	1E	1F	20	21	22	23	24	25	26	27
54	55	56	57	58	5 9	5A	5B	5C	5D	5 E	5F	60	61	62	63	64	65	66	67

9.Character Generator ROM Pattern

Table.2

67-64 63-60	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000	CG RAM (1)															
0001	(2)															
0010	(3)															
0011	(4)															
0100	(5)															
0101	(6)															
0110	7)															
0111	(8)															
1000	(1)															
1001	(2)															
1010	(3)															
1011	(4)															
1100	(5)															
1101	(6)															
1110	(7)															
1111	(8)															

10.Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

	Environmental Test		
Test Item	Content of Test	Test Condition	Not e
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity storage	The module should be allowed to stand at 60 °C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation $-20^{\circ}\text{C} \qquad 25^{\circ}\text{C} \qquad 70^{\circ}\text{C}$ $30\text{min} \qquad 5\text{min} \qquad 30\text{min}$	-20°C/70°C 10 cycles	
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330Ω CS=150pF 10 times	<u> </u>

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

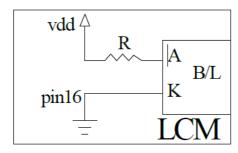
11.Backlight Information

Specification

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	_	128	160	mA	V=5.0V
Supply Voltage	V	4.9	5.0	5.1	V	_
Reverse Voltage	VR	_	_	5	V	_
Luminance	IV	1040	1200		CD/M ²	H ED_120m A
(Without LCD)	IV	1040	1300	_	CD/M²	ILED=128mA
LED Life Time						
(For Reference	λp	620	625	630	nm	ILED=128mA
only)						
						ILED=128mA
Color	_	_	50K	_	Hr.	25℃,50-60%RH,
						(Note)
	White (high	gh light)				

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Drive from Vdd, Pin 16



12.Inspection specification

NO	Item	Criterion				AQL
01	Electrical Testing	Missing charact Display malfund No function or of Current consum LCD viewing and Mixed product Contrast defect	er, dot or ction. no display nption exc gle defect. types.	eeds product speci	fications.	0.65
02	Black or white spots on LCD (display only)	three white or b	olack spot		mm, no more than s or lines within	2.5
03	LCD black spots, white spots, contaminatio n (non- display)	3.1 Round type $\Phi=(x+y)/2$ X 3.2 Line type : (As followi	$Φ \le 0.10$ $0.10 < Φ \le 0.20$ $0.20 < Φ \le 0.25$ $0.25 < Φ$ mg drawing) Width $W \le 0.02$	Acceptable Q TY Accept no dense 2 1 0 Acceptable Q TY Acceptable Q TY Accept no dense	2.5
		→ L +	L≦3.0 L≦2.5	0.02 < W ≤ 0.03 0.03 < W ≤ 0.05 0.05 < W	As round type	2.5
04	Polarizer bubbles	If bubbles are v judge using blac specifications, r to find, must ch specify direction	ck spot not easy eck in	Size Φ $Φ \le 0.20$ $0.20 < Φ \le 0.50$ $0.50 < Φ \le 1.00$ $1.00 < Φ$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5

NO	Item	Criterion			AQL
05	Scratches	Follow NO.3 LCD black	spots, white spots, con	tamination	
		Symbols Define:			
		x: Chip length y	: Chip width z: Chi	p thickness	
		k: Seal width t	:: Glass thickness a: LC	D side length	
		L: Electrode pad lengt	h:		
		6.1 General glass chip	:		
		6.1.1 Chip on panel su	rface and crack between	n panels:	
			A LA	L'A BRITAN	
		z: Chip thickness	y: Chip width	x: Chip length	
		Z≦1/2t	Not over viewing	x≦1/8a	
06	Chipped		area		2.5
	glass	1/2t < z ≦ 2t	Not exceed 1/3k	x≦1/8a	
		⊙ If there are 2 or mo	re chips, x is total length	of each chip.	
		6.1.2 Corner crack:	y		
		z: Chip thickness	y: Chip width	x: Chip length	
		Z≦1/2t	Not over viewing area	x≦1/8a	
		1/2t < z ≤ 2t	Not exceed 1/3k	x≦1/8a	
		⊙ If there are 2 or mo	re chips, x is the total le	ngth of each chip.	

NO	Item	Criterion			AQL
		Symbols :			
		x: Chip length y: Chip wi	dth z: Chip thi	ckness	
			nickness a: LCD sid		
		L: Electrode pad length			
		6.2 Protrusion over terminal :			
	Glass	6.2.1 Chip on electrode pad :			
06		y: Chip width x: Chip length z: Chip thickness $y \le 0.5 \text{mm}$ $x \le 1/8 \text{a}$ $0 < z \le t$ 6.2.2 Non-conductive portion:		2.5	
		y: Chip width x:	Chip length	z: Chip thickness	
		y≦ L x≦	≦1/8a	$0 < z \le t$	
		⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must			
		remain and be inspected according to electrode terminal specifications.			
		\odot If the product will be heat sealed by the customer, the alignment mark not			
		be damaged.			
		6.2.3 Substrate protuberance and internal crack.			
		y: width x: length		x: length	
			$y \le 1/3L$ $x \le a$		
уу					

Soldering Scale Cracked glass The LCD with extensive crack is not acceptable. 2.5	NO	Item	Criterion	AQL
Backlight elements 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications. 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 2.5 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB 2.5 2.5 3.6 3.7 3.7 3.7 3.7 3.8 3.8 3.8 3.8	07	Cracked glass	The LCD with extensive crack is not acceptable.	
Soldering Using LCD spot, lines and contamination standards.	08		8.1 Illumination source flickers when lit.	0.65
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10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB 2.5 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 2.5			seal area on the PCB. And there should be no more than three	
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11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 2.5	11	Soldering	11.1 No un-melted solder paste may be present on the PCB.	2.5
11 Soldering oxidation or icicle. 11.3 No residue or solder balls on PCB. 2.5			· · ·	
11.3 No residue or solder balls on PCB. 2.5				
11.4 No short circuits in components on PCB. 0.65			11.3 No residue or solder balls on PCB.	2.5
			11.4 No short circuits in components on PCB.	0.65

NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface	2.5
		Pin (OLB) of TCP.	
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface	2.5
		pin must be present or look as if it cause the interface pin to	
		sever.	2.5
	General	12.6 The residual rosin or tin oil of soldering (component or chip	
12		component) is not burned into brown or black color.	2.5
	appearance	12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging	
		specification sheet.	0.65
		12.11 Product dimension and structure must conform to product	
		specification sheet.	0.65
		12.12 Visual defect outside of VA is not considered to be	
		rejection.	

13.Material List of Components for RoHs

1. Producer hereby declares that all of or part of products including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

2.Process for RoHS requirement: (only for RoHS inspection)

- (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.;

Connector soldering wave or hand soldering: 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°C;

Recommended customer's soldering temp. of connector: 280°C, 3 seconds.

14.Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.